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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
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Complete if Known

Application Number	10/607,738
Filing Date	June 26, 2003
First Named Inventor	Houle, Sabina
Group Art Unit	1725
Examiner Name	Kiley Stoner

Attorney Docket No: 884.832US1

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EXAMINER

*[Signature]*

DATE CONSIDERED 5/18/05